# 2SK3042

## Silicon N-Channel Power F-MOS FET

#### ■ Features

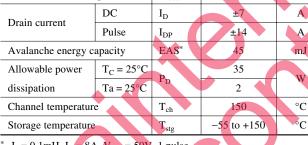
- Avalanche energy capacity guaranteed: EAS > 45mJ
- $\bullet$  High-speed switching:  $t_f = 30$ ns
- No secondary breakdown

#### Applications

- Contactless relay
- Diving circuit for a solenoid
- Driving circuit for a motor
- Control equipment
- Switching power supply

### ■ Absolute Maximum Ratings (T<sub>C</sub> = 25°C)

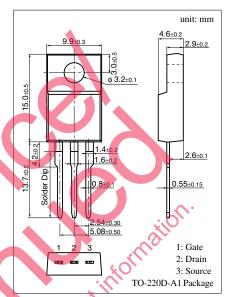
Parameter		Symbol	Ratings	Unit
Drain to Source breakdown voltage		V <sub>DSS</sub>	250	V
Gate to Source voltage		V <sub>GSS</sub>	±20	V
Drain current	DC	I <sub>D</sub> ±7		A
	Pulse	$I_{\mathrm{DP}}$	±14	A
Avalanche energy capacity		EAS*	45	mJ
Allowable power	$T_C = 25^{\circ}C$	D	35	W
dissipation	Ta = 25°C	$P_{\rm D}$	2	W
Channel temperature		T <sub>ch</sub>	150	°C
Storage temperature	$T_{stg}$	-55 to +150	°C	



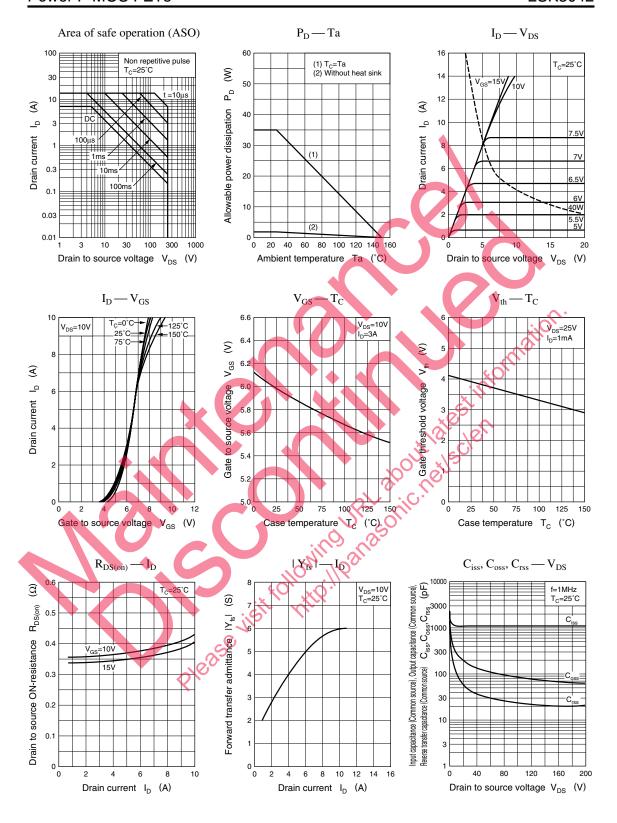


## ■ Electrical Characteristics ( $T_C = 25$ °C

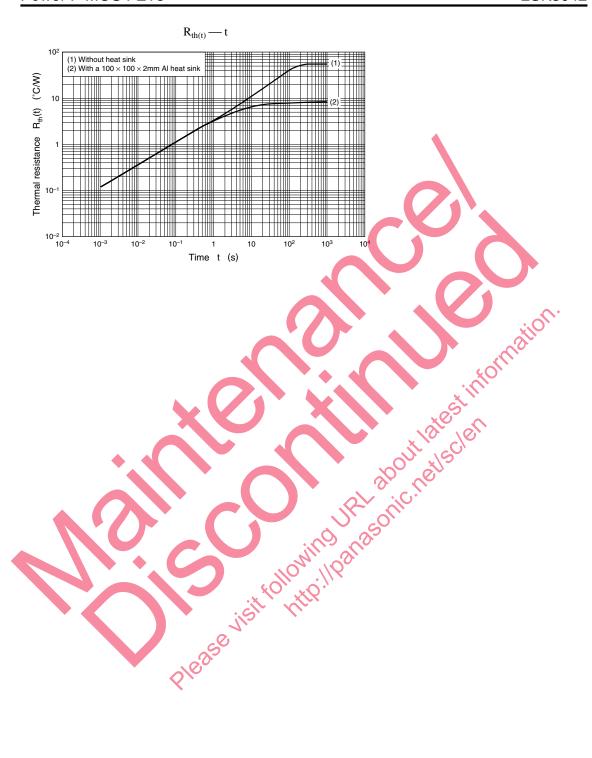
		- 7	9-			2.54±0.30	100	)			
Drain to Source breakdown voltage		V <sub>DSS</sub>	250	V		5.08±0.50	Si	1.0			
Gate to Source voltage		V <sub>GSS</sub>	±20	V		2 3	MI	1: Gate 2: Drain			
Drain current	DC	$I_D$	±7	A			TO 220D	3: Source A1 Package			
Diam current	Pulse	$I_{\mathrm{DP}}$	±14	A	<u> </u>	4/11.	10-220D-	AlFackage			
Avalanche energy capacity		EAS*	45	mJ	×	65,					
Allowable power	$T_C = 25^{\circ}C$	D	35	W.	10	101					
dissipation	Ta = 25°C	$P_{\rm D}$	2	W	ali isch						
Channel temperature		T <sub>ch</sub>	150	°C	o si						
Storage temperature		$T_{stg}$	-55 to +150	°C							
Drain current  Pulse $I_{DP}$ $\pm 14$ A  Avalanche energy capacity  EAS* $45$ mJ  Allowable power $T_C = 25^{\circ}C$ dissipation $T_C = 25^{\circ}C$ $T_C = 25^{\circ}C$ Channel temperature $T_{Ch}$ Storage temperature $T_{Stg}$ $T_{Stg}$ $T_{Stg}$ $T_{Stg}$ To-220D-A1 Package  10-220D-A1 Package  10-220D-A1 Package  10-220D-A1 Package  10-220D-A1 Package											
Paramete	er	Symbol	Conditions		min	typ	max	Unit			
Drain to Source cut-	off current	I <sub>DSS</sub>	$V_{DS} = 200V, V_{GS} = 0$				0.1	mA			
Gate to Source leak	age current	$I_{GSS}$	$V_{GS} = \pm 20V, V_{DS} = 0$				±1	μΑ			
Drain to Source break	down voltage	V <sub>DSS</sub>	$I_D = 1 \text{mA}, V_{GS} = 0$		250			V			
Gate threshold voltage $V_{th}$		$V_{\rm DS} = 10  \text{V},  I_{\rm D} = 1  \text{mA}$		1		5	V				
Drain to Source ON-resistance R <sub>DS(on)</sub>		R <sub>DS(on)</sub>	$V_{GS} = 10V, I_D = 5A$			0.4	0.6	Ω			
Forward transfer admittance $Y_{fs}$		Y <sub>fs</sub>	$V_{DS} = 10V, I_D = 5A$		2.7	4.7		S			
Diode forward volta	Diode forward voltage $V_{DSF}$ $I_{DR} = 8A, V_{GS} = 0$				-1.7	V					
Input capacitance (Con	mmon Source)	C <sub>iss</sub>				1100		pF			
Output capacitance (Common Source) C <sub>oss</sub>		$V_{DS} = 10V, V_{GS} = 0, f = 1MHz$			200		pF				
Reverse transfer capacitance	(Common Source)	C <sub>rss</sub>				60		pF			
Turn-on time (delay	time)	t <sub>d(on)</sub>				20		ns			
Rise time t <sub>1</sub>		t <sub>r</sub>	$V_{GS} = 10V, I_D = 5A$			20		ns			
Turn-off time (delay time)		t <sub>d(off)</sub>	$V_{DD} = 100V, R_{L} = 20\Omega$			130		ns			
Fall time		$t_{\rm f}$				30		ns			



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